

2019 International 3D Systems Integration Conference (3DIC 2019)

**Sendai, Japan
8 – 10 October 2019**



**IEEE Catalog Number: CFP19DIC-POD
ISBN: 978-1-7281-4871-7**

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IEEE Catalog Number:	CFP19DIC-POD
ISBN (Print-On-Demand):	978-1-7281-4871-7
ISBN (Online):	978-1-7281-4870-0

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